• Supplementary File •

$Hf_{0.5}Zr_{0.5}O_2$ 1T-1C FeRAM arrays with excellent endurance performance for embedded memory

Wenwu XIAO^{1,2}, Yue PENG^{1,3*}, Yan LIU^{1,3}, Huifu DUAN², Fujun BAI², Bing YU², Qiwei REN², Xiao YU³, Genquan HAN^{1,3,4*}

¹School of Microelectronics, Xidian University, Xi'an 710071, China;
²Xi'an UniIC Semiconductors, Xi'an 710071, China;
³Research Center for Intelligent Chips, Zhejiang Lab, Hangzhou 311121, China;
⁴Hangzhou Institute of Technology, Xidian University, Hangzhou 311200, China

Appendix A Ferroelectric characteristics of the HZO film in the arrays



Figure A1 (a) *P*-*V* loops of 1C with different diameters. (b) The cumulative probability of $2P_r$ for 1C with a diameter of 8 µm. (c) Switching characteristics, (d) retention, and (e) endurance of 1C.

In order to verify the ferroelectric characteristics of the HZO film in the arrays, P-V curves for different sizes of BEOL integrated single capacitor were measured and shown in Figure A1(a), and the results indicate that all the size of a single capacitor (the diameters of 8 µm, 10 µm, 12 µm, and 16 µm) can exhibit excellent ferroelectric behavior. The cumulative probability of $2P_r$ at different sweeping ranges for the single capacitor with a diameter of 8 µm was shown in Figure A1(b). Fifty capacitors were measured for each condition. A similar variation of $2P_r$ at different applied V is observed. In addition, Figure A1(c) shows the P switching characteristics of a single capacitor with a diameter of 8 µm [1]. A fast operation speed of 30 ns and a switching polarization (P_{SW}) above 33 µC/cm² with 20 nm HZO film are achieved. Figure A1(d) shows the retention characteristics of the retention test up to 10⁴ s. The endurance of the single capacitor is characterized by the stable P-V curves over 10¹¹ cycles at 1 MHz. The evolution of the P_r and the coercive voltage (V_c) values are presented in Figure A1(e). The good endurance and the decent retention performance ensure excellent reliability for the 1T-1C FeRAM.

Appendix B 16 kbit 1T-1C array demonstration

The schematics and simplified timing diagram for "write" and "read" operations of 1T-1C structure with sensitive amplifier (SA) are shown in Figure B1(a) and (b), respectively. Here, the word line (WL), bit line (BL), plate line (PL), column select line (CSL), the local data line (LDQ), and pre-charge (PRE) are defined. During the "write" operation, WL is turned on, firstly. And

^{*} Corresponding author (email: ypeng@xidian.edu.cn, gqhan@xidian.edu.cn)



Figure B1 Schematics and simplified timing diagram for (a) write and (b) read operations of 1T-1C structure with sensitive amplifier (SA). Word line (WL), bit line (BL), plate line (PL), column select line (CSL), local data line (LDQ), and pre-charge (PRE) are defined. (c) Definition of $C_{\rm FE}$ in formula (B1).

then, the PL increases to $V_{\rm high}$ and subsequently is pulled back to $V_{\rm low}$. BL is raised to $V_{\rm high}$ to write "1" during the PL is at $V_{\rm low}$, and BL is driven to $V_{\rm low}$ to write "0" during the PL is at $V_{\rm high}$. Finally, deactivating the WL leaves this state undisturbed until the next access. Similarly, during the "read" operation, data is read from the selected cell to SA *via* PL pulsing and then transferred to LDQ. The potential of BL ($V_{\rm BL}$) is compared to a reference voltage ($V_{\rm ref}$) with one SA per BL and converted into a digital SA outputs signal. The $V_{\rm BL}$ is determined by

$$V_{BL} = \frac{C_{FE}}{C_{FE} + C_{BL}} \times V_{PL} \tag{B1}$$

Where $V_{\rm PL}$ is the voltage of PL, $C_{\rm BL}$ is the BL capacitor, and $C_{\rm FE}$ is the ferroelectric capacitor. As shown in Figure B1(c), the $C_{\rm FE}$ is C_0 if a data "0" is stored, and is C_1 if a data "1" is stored, depending on the memory state of the cell. $V_{\rm BL}$ elevates at either $V_{\rm BL}^{\rm C0}$ ($C_{\rm FE} = C_0$) or $V_{\rm BL}^{\rm C1}$ ($C_{\rm FE} = C_1$). Here, the memory window (MW) of the 1T-1C cell is defined as the difference $\Delta V_{\rm BL} = V_{\rm BL}^{\rm C1} \cdot V_{\rm BL}^{\rm C0}$.



Appendix C FeRAM test chip with different blocks

Figure C1 Schematics of the FeRAM test chip with different blocks, including row (row address, WL decoding and WL driver *et al.*,), column (column address, CSL and SA et al.,), cell-matrix. The main signals and their function were listed.

Appendix D The functional "read" and "write" operations for "1" and "0" in the FeRAM array

For the "read" operation, the BLs are driven to $V_{\rm SS}$, and WL is turned on, firstly. Then, $V_{\rm BL}$ rises to $V_{\rm BL}{}^{\rm C0}$ in case of "0" and $V_{\rm BL}{}^{\rm C1}$ in case of "1" via PL pulsing. Secondly, by setting $V_{\rm BLN}$ to $V_{\rm ref}$, during SA operation, BL rises to $V_{\rm BLH}$ (data "1")



Figure D1 Time diagram of (a) write and (b) read operation of array-level FeRAM.

or falls to V_{SS} (data "0"), achieving data transfer from the cell to the SA (like DRAM active operation). Next, the data in SA is read out to LDQ when the CSLE signal rises to high. Thirdly, the cells are written back. Finally, BLs are pre-charged and WL is turned off. For the "write" operation, the data in SA originated from the cell, is overwritten from the external in/out (I/O) interface during CSLE signal rise to high. The rest of the "write" operation is similar to that of the "read" operation.

References

1 Li Y, Li J, Liang R, et al. Switching dynamics of ferroelectric HfO₂-ZrO₂ with various ZrO₂ contents. Appl. Phys. Lett, 2019, 114: 142902.